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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
UMESH SHARMA	03/09/2007
HARRY YUE GEE	03/09/2007
PHILLIP GENE HOLLAND	03/09/2007

RECEIVING PARTY DATA

Name:	CALIFORNIA MICRO DEVICES	
Street Address:	490 N. McCarthy Boulevard	
Internal Address:	Suite 100	
City:	Milpitas	
State/Country:	CALIFORNIA	
Postal Code:	95035	

PROPERTY NUMBERS Total: 1

Property Type	Number	
Application Number:	11685085	

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NAME OF SUBMITTER:	David A. Jakopin

PATENT REEL: 018996 FRAME: 0903

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Total Attachments: 2 source=doc302#page1.tif source=doc302#page2.tif

> PATENT REEL: 018996 FRAME: 0904

Attorney's Docket No. 010549-0359379 PATENT

Client Reference: CMD-038

For: U.S. Rights and Foreign Rights

For: U.S. Application

By: Inventors

ASSIGNMENT OF INVENTION

In consideration of the employment by ASSIGNEE of ASSIGNORS, and for other good and valuable consideration, the receipt of which is hereby acknowledged,

ASSIGNORS: UMESH SHARMA

1620 Hope Drive, #517 Santa Clara, CA 95054

HARRY YUE GEE 180 Elm Court, #1502 Sunnyvale, CA 94086

PHILLIP GENE HOLLAND

17150 Pine Ave.

Los Gatos, CA 95032

hereby sell, assign and transfer to

ASSIGNEE: CALIFORNIA MICRO DEVICES

490 N. McCarthy Boulevard #100

Milpitas, CA 95035

and the successors, assigns and legal representatives of the ASSIGNEE the entire right, title and interest for the United States and its territorial possessions and in all foreign countries, including all rights to claim priority, in and to any and all improvements which are disclosed in the invention entitled:

A METHOD OF MAKING RELIABLE WAFER LEVEL CHIP SCALE PACKAGE SEMICONDUCTOR DEVICES

and which is found in (37 C.F.R. § 3.21) U.S. patent application Serial No. 11/685,085 filed March 12, 2007, and any legal equivalent thereof in a foreign country, including the right to claim priority and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuation, division, renewal, or substitute thereof, and as to letters patent any reissue or re-examination thereof.

ASSIGNORS hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

ASSIGNORS further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNORS and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue

Assignment of Invention-page 1 of 2

and enforce said application, said invention	and said Letters Patent and said equivalents thereof which
may be necessary or desirable to carry out the	e purposes thereof.
Date: 3 09 67	Maren /horn
• •	Signature of UMESH SHARMA
Date: 3/09/07	Harry Une See
•	Signature of HARRY YUE GEE
Date:	Pullip Gove Holland
	Signature of PHILLID CENE HOLL AND

Assignment of Invention-page 2 of 2

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RECORDED: 03/12/2007

PATENT REEL: 018996 FRAME: 0906